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## Advanced Electronic Packaging Technology: From Hard to Soft

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Deadline for manuscript  
submissions:

**closed (20 May 2024)**

### Message from the Guest Editors

This Special Issue will address advances in Electronic Packaging Technology, including design, structure, material, processing, and testing of electronic and photonic devices. Electronic devices have been rapidly developing with the growing necessities of high-computing, low-power consumption, miniaturization, and multi-function in computers and consumer electronics products.

Soft electronic packaging represents one of the most promising approaches to form imperceptible and comfortable interfaces of human and electronic devices. In this regard, the demonstration of advanced soft materials, structures, and design in advanced electronic packaging is strongly demanded to comply with the requirements of the developments of soft electronic devices.

Original papers are solicited on all types of advanced electronic packaging technologies involving designs, structures, materials, processing, and testing. For more information, please click into the website at: [https://www.mdpi.com/journal/materials/special\\_issues/electronic\\_packaging](https://www.mdpi.com/journal/materials/special_issues/electronic_packaging) (or: [mdpi.com/si/103244](https://www.mdpi.com/si/103244))



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# Special Issue



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## Message from the Editor-in-Chief

*Materials* (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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